

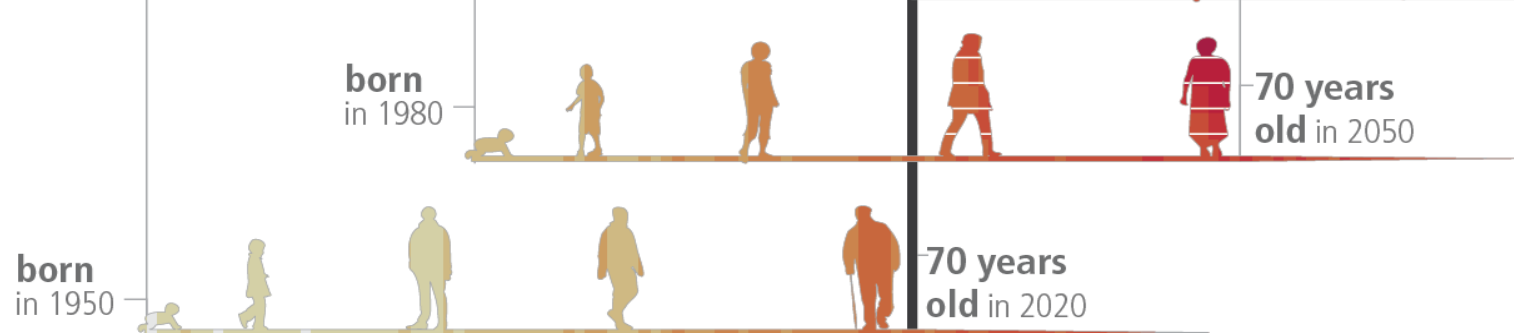
Closing the Sustainability Gap in Nano- and Microelectronics Research and Education

Carol Handwerker
Purdue University

Korea – US Forum – Seoul
3-4 April 2023



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ACCELERATING TECHNOLOGY TRANSITION

Bridging the Valley of Death for Materials and Processes in Defense Systems

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COMMITTEE ON ACCELERATING TECHNOLOGY TRANSITION

DIRAN APELIAN, Worcester Polytechnic Institute, *Chair*

ANDREW ALLEYNE, University of Illinois, Urbana-Champaign

CAROL A. HANDWERKER, National Institute of Standards and Technology

DEBORAH HOPKINS, Lawrence Berkeley National Laboratory

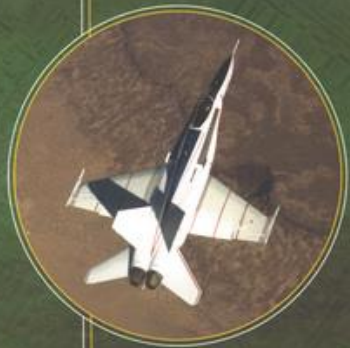
JACQUELINE A. ISAACS, Northeastern University

GREGORY B. OLSON, Northwestern University

RANJI VAIDYANATHAN, Advanced Ceramics Research, Inc.

SANDRA DeVINCENT WOLF, Consultant

- Creating a culture for innovation and rapid technology transition,
- Methodologies and approaches, and
- Enabling tools and databases.



NATIONAL RESEARCH COUNCIL
OF THE NATIONAL ACADEMIES

NSF Integrated Education and Research Traineeship Program
IGERT: Global Traineeship in Sustainable Electronics

Our Vision

How do we as educators, scientists, and engineers create a sustainable eco-system for educating, training and empowering students to be leaders in sustainability?

*iNEMI, Indian Institute of Management - Udaipur
collaboration with industry, NGOs, research institutions, govt.*

Convergence

- CHIPS Act: \$52B – Workforce Development Focus
- SRC Roadmap Sustainability and Energy Efficiency (part of Roadmap for Microelectronics and Packaging Technologies)

Workforce Development for Sustainable Electronics

- A social contract – students, educators, companies for jobs. *We are responsible for environmental and societal impacts we design and use*

SRC F Susta

2.1. Intro

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▪ **Grand Challenge**

“achieving a 1000x to 1,000,000x increase in computing energy efficiency over the next two decades”

▪ **Trends/ Drivers**

“...the energy efficiency of computing has improved exponentially, enabled by the scaling provided by Moore’s law it has also had the effect that orders of magnitude more computing is consumed each decade.”

“This increasing appetite for computing, with the slowing of scaling for the newer technologies, is why information technology is poised to consume a major fraction of the world’s energy in the coming decades”

▪ **Promising Technologies**

“The combination of advanced packaging, emerging technologies, and codesign with new architectures, devices with algorithms and software will support the SRC Decadal Plan goal of achieving a 1000x to 1,000,000x increase in computing energy efficiency over the next two decades”

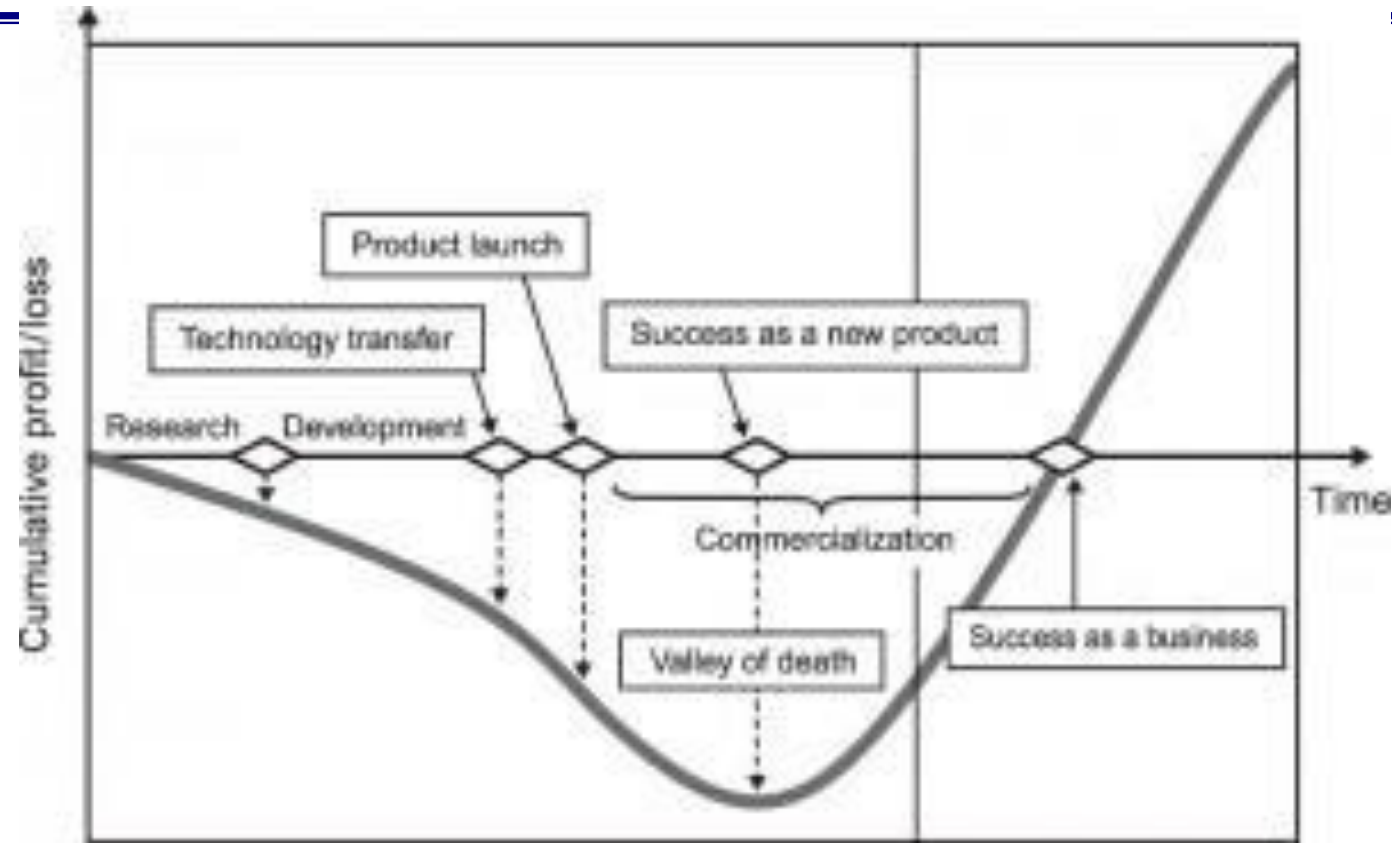
“Creating a full stack that includes the chiplet, custom domain-specific accelerator designs, system software, and application drivers that can be modular and usable across computing technology advances especially using cross-disciplinary innovations from materials to complex heterogeneous systems enabled by advanced packaging.”



SEMICONDUCTOR CLIMATE CONSORTIUM

FOUNDING MEMBERS

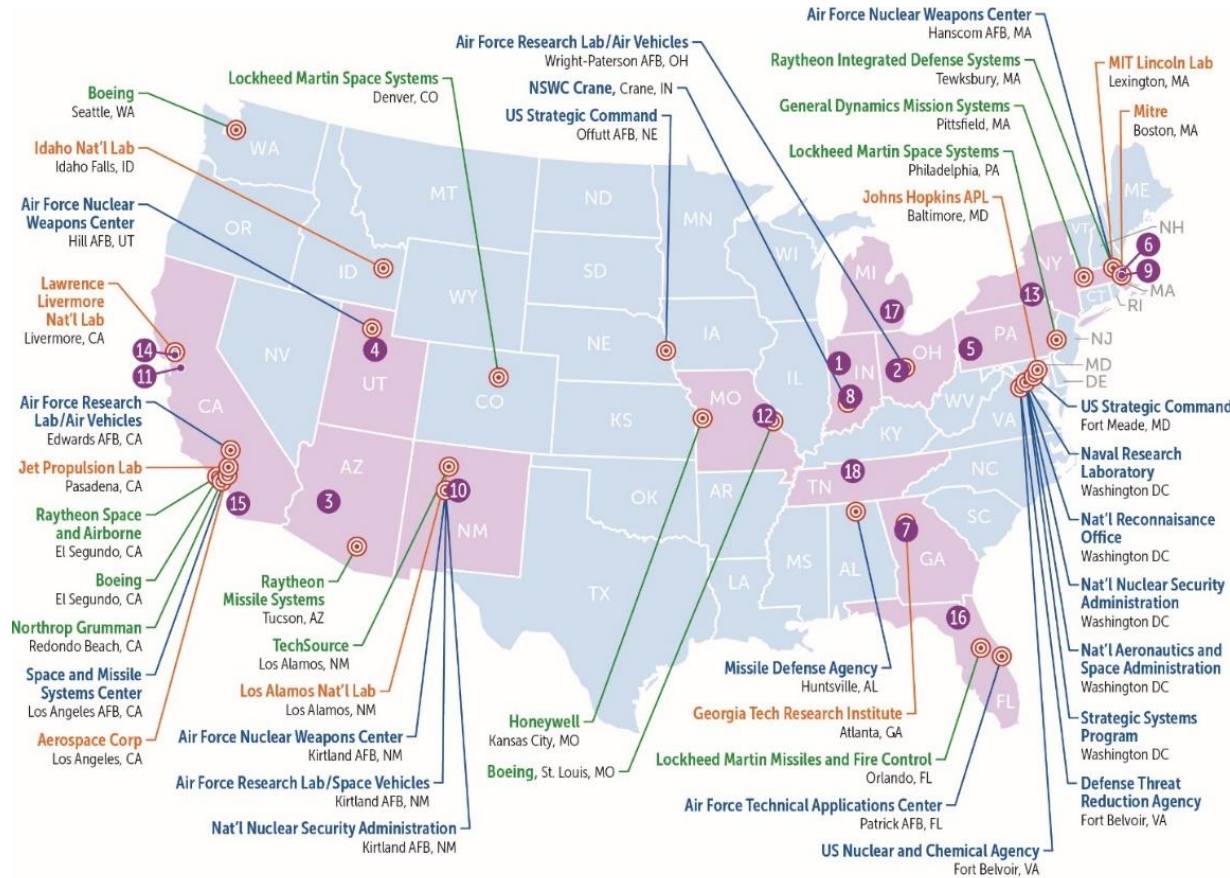
Advantest • AICELLO • AMD • ams OSRAM Group • Analog Devices • Applied Materials • Arkema • ASE
ASM • ASML • ASMPT • Athinia™ • Axcelis • Brewer Science • DAS Environment Expert
Dongjin Semichem • DuPont • EBARA • Edwards • Entegris • GlobalFoundries • GlobalWafers • Google
Hermes Epitek • Hitachi High-Tech • imec • Intel Corporation • JSR • KLA • KOKUSAI ELECTRIC
Kulicke & Soffa • Lam Research • Lasertec • Longi • Marvell • Micron • Microsoft • Monument Chemical
MYCRONIC • Nanya Technology • Nikon • NXP • onsemi • Ovivo • Pfeiffer Vacuum • Plexus Corp.
Samsung Electronics • Schneider Electric • SCREEN Semiconductor Solutions • Showa Denko Materials
SK hynix • SkyWater • Sphera • STMicroelectronics • Sumitomo Chemical • Tokyo Electron Limited
Tokyo Ohka Kogyo • Tokyo Seimitsu • Tri Chemical Laboratories • TSMC • UCT • ULVAC
UTAC • VAT Group • Western Digital



SCALE (Scalable Asymmetric Lifecycle Engagement): A *Workforce Development Prototype* for US Defense Microelectronics

- Creating a culture for innovation and rapid technology transition,
- Methodologies and approaches, and
- Enabling tools and databases.

SCALE will provide DOD/GOV/DIB with a more effective pipeline and an asymmetric microelectronics workforce advantage



Target Institutions		
Government	Federally Funded Research and Development Centers	Industry
Partners (Institution Topic Areas*)		
1 Purdue University, West Lafayette, IN (RH, HIAP, SC, ESS, SoC)	7 Georgia Institute of Technology, Atlanta, GA (RH, HIAP, SC, ESS, SoC)	13 State University of New York at Binghamton, NY (HIAP)
2 Air Force Institute of Technology, Wright-Patterson Air Force Base, OH (RH)	8 Indiana University, Bloomington, IN (ESS, SoC)	14 University of California, Berkeley, CA (ESS, SoC)
3 Arizona State University, Tempe, AZ (RH, HIAP, SC)	9 Massachusetts Institute of Technology, Boston, MA (ESS, SoC)	15 University of California, San Diego, CA (ESS)
4 Brigham Young University, Provo, UT (RH)	10 Sandia National Laboratory, Albuquerque, NM (RH)	16 University of Florida, Gainesville, FL (SC)
5 Carnegie Mellon University, Pittsburgh, PA (ESS, SoC)	11 Sandia National Laboratory, Livermore, CA (RH)	17 University of Michigan, Ann Arbor, MI (RH)
6 Draper Laboratory, Cambridge, MA (RH)	12 St. Louis University (RH)	18 Vanderbilt University, Nashville, TN (RH)

*RH = Radiation Hardened, HIAP = Heterogeneous Integration/Advanced Packaging, SC = Supply Chain, ESS = Embedded Systems Security, SoC = System on Chip

Technical Verticals

- Radiation-hardened technology:**
1. Vanderbilt
 2. Air Force Institute of Technology
 3. St. Louis University
 4. Brigham Young University
 5. Arizona State University
 6. Georgia Tech
 7. Purdue University
 8. Indiana University
 9. New Mexico State University
 10. UT-Chattanooga

- Heterogeneous integration and advanced packaging:**
1. Purdue University
 2. Georgia Tech
 3. SUNY-Binghamton
 4. Arizona State University

- System on Chip:**
1. Ohio State University
 2. Georgia Tech
 3. Purdue University
 4. UC-Berkeley

- Supply Chain Awareness:**
1. Purdue University
 2. University of Florida

- Embedded Systems Security:**
1. Indiana University
 2. IUPUI
 3. Notre Dame

SCALE scalability demonstrated by PPAP National Network

SCALE Pathways for Undergraduate Trainees

First Year

Core curriculum

Fall & Spring: Introduce Microelectronics (ME) modules into core courses, **Spring:** Recruiting - Open House/Call Out, research projects, seminars, workshops, bootcamp

Summer: **Possible DOD/GOV/DIB Internship or REU**

Second Year

Core curriculum

Fall & Spring: Introduce ME modules in disciplinary core courses, research projects, seminars, workshops

Spring: Open House, Application, selection, & sign-up, **Orientation & field trips**

Summer: **Likely DOD/GOV/DIB Internship or REU**

Third Year

Core curriculum

Fall & Spring: Multi-disciplinary core courses for program (1Cr, 3Cr), Mentored team-based research, Defense Microelectronics Research Fellowship – **Research mentors & seminars**

Summer: **Guaranteed internship with DOD/GOV/DIB facilities**

Fourth Year

Core curriculum

Fall: Focused topical area course for team-based project (Capstone Senior Design, Focused Area, or interdisciplinary), Mentored team-based research, Defense Microelectronics Research Fellowship, technical electives relevant to focus topics - **Research mentors & seminars, work with interns to select technical electives useful for future employment**

Spring: Interdisciplinary course for focused topical area, Mentored team-based research, Defense Microelectronics Research Fellowship, technical electives relevant to focused topic - **Research mentors & seminars, work with interns to select technical electives useful for future employment**

Summer: Graduation → hired by DOD/DIB, admitted to graduate school for DOD topic research



DoD and universities defined the fundamental knowledge, skills, and abilities (KSAs) needed across all microelectronics fields.

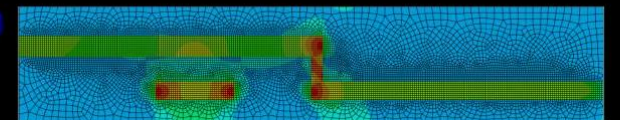
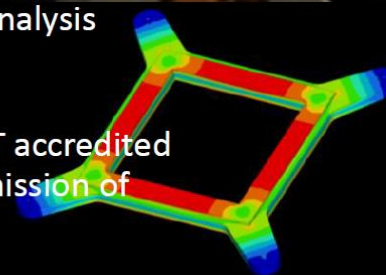
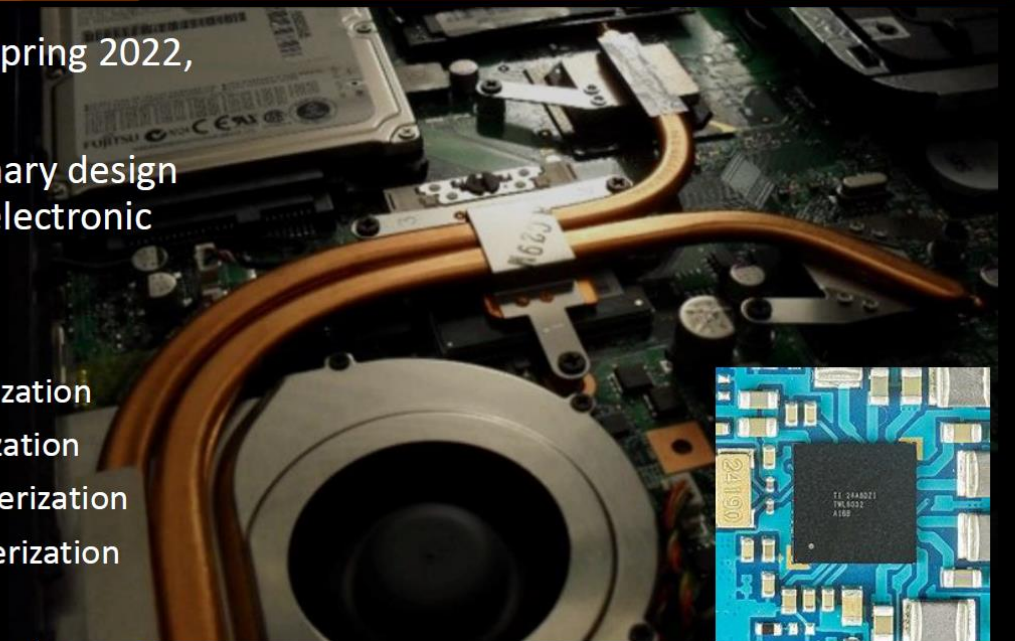
Co-created and co-delivered by Purdue, Georgia Tech, Arizona State, Vanderbilt, SUNY/Binghamton,

Asynchronous
Scaleable

ME 597 ECE 595 MSE 597

Introduction to Electronics Packaging and Heterogeneous Integration

- Instructor: Ganesh Subbarayan, Spring 2022, 3 credits
- Learn the basics of multi-disciplinary design and characterization of modern electronic components and assemblies
- Topics:
 - Electrical Design and Characterization
 - Thermal Design and Characterization
 - Mechanical Design and Characterization
 - Material Selection and Characterization
 - Package Fabrication
 - Statistical Modeling and Data Analysis
- Prerequisites:
 - Junior-level standing in an ABET accredited engineering curriculum or permission of course instructor



David N Halbrooks
Email: dhalbroo@purdue.edu

Common Pool Resources

Commons: A resource shared by many people who depend on it for their livelihoods

- In context of products, there are multiple “commons”
 - the environment - creating pollution and wasting embedded resources
 - the products themselves, their components, and retaining value to society

Natural

- Fisheries
- Forests
- Groundwater
- Irrigation Systems
- Rivers
- Air

Man-Made

- E-waste
- Paper
- Plastic
- Food
- Products
- Minerals



Common Pool Resources

Commons: A resource shared by many people who depend on it for their livelihoods

Our students as a “commons”

It is up to us to work together and with them to help them become leaders in sustainability

ty

Avoid

“The Tragedy of the Commons”

- Forests
- Groundwater
- Irrigation Systems
- Rivers
- Air
- Paper
- Plastic
- Food
- Products
- Minerals



Organizing Framework – Ostrom - 2009 Nobel Prize

PERSPECTIVE

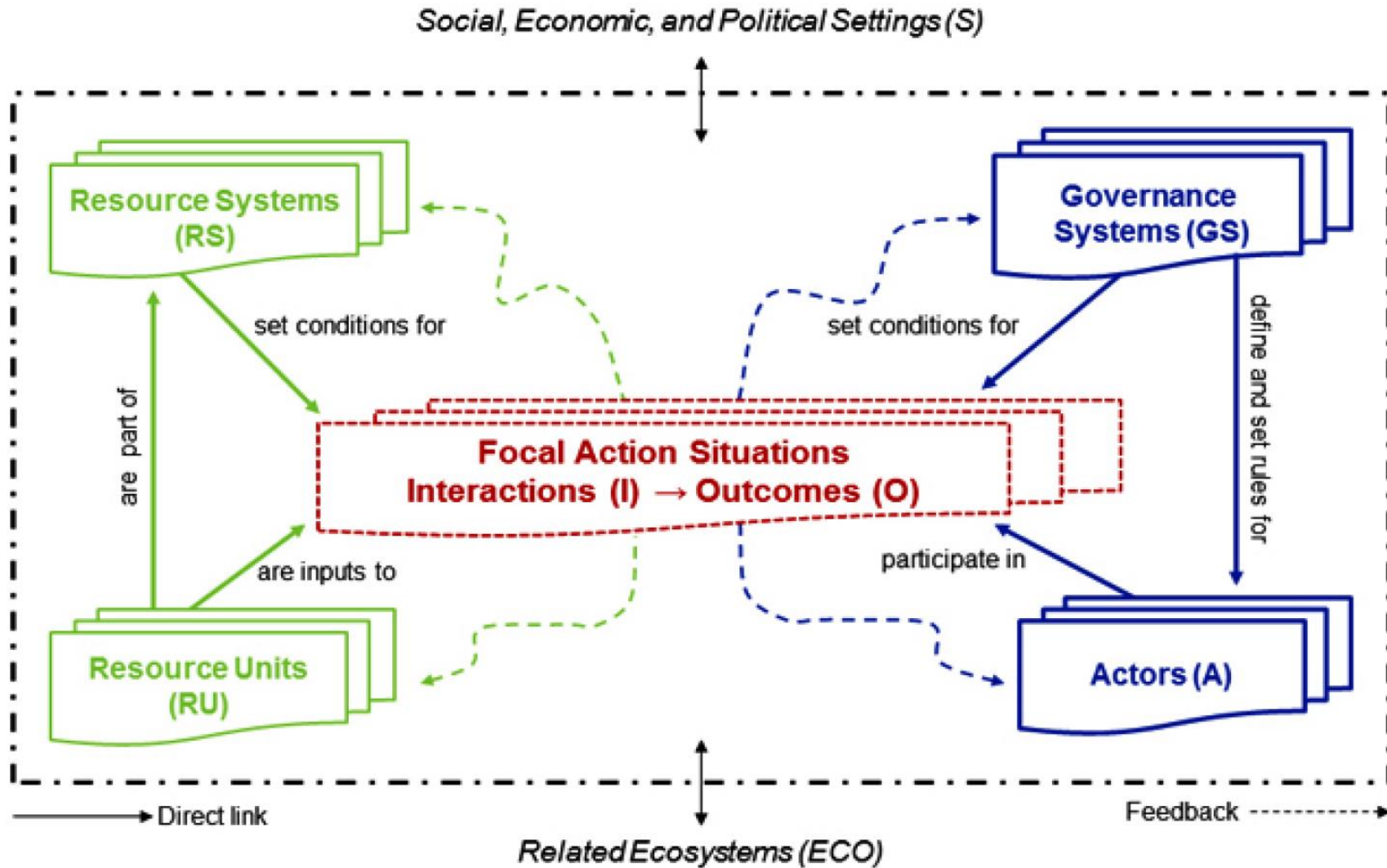
SCIENCE VOL 325 24 JULY 2009

A General Framework for Analyzing Sustainability of Social-Ecological Systems

Elinor Ostrom^{1,2*}

A major problem worldwide is the potential loss of fisheries, forests, and water resources. Understanding of the processes that lead to improvements in or deterioration of natural resources is limited, because scientific disciplines use different concepts and languages to describe and explain complex social-ecological systems (SESs). Without a common framework to organize findings, isolated knowledge does not cumulate. Until recently, accepted theory has assumed that resource users will never self-organize to maintain their resources and that governments must impose solutions. Research in multiple disciplines, however, has found that some government policies accelerate resource destruction, whereas some resource users have invested their time and energy to achieve sustainability. A general framework is used to identify 10 subsystem variables that affect the likelihood of self-organization in efforts to achieve a sustainable SES.

Framework for Sustainable Systems for the Commons (Ostrom)



Social, economic, and political settings (S)

- S1 – Economic development
- S2 – Demographic trends
- S3 – Political stability

- S4 – Other governance systems
- S5 – Markets
- S6 – Media organizations
- S7 – Technology

Resource systems (RS)

- RS1 – Sector
- RS2 – Clarity of system boundaries
- * RS3 – Size of resource system
- RS4 – Human-constructed facilities
- * RS5 – Productivity of system
- RS6 – Equilibrium properties
- * RS7 – Predictability of system dynamics
- RS8 – Storage characteristics
- RS9 – Location

Resource units (RU)

- * RU1 – Resource unit mobility
- RU2 – Growth or replacement rate
- RU3 – Interaction among resource units
- RU4 – Economic value
- RU5 – Number of units
- RU6 – Distinctive characteristics
- RU7 – Spatial and temporal distribution

Governance systems (GS)

- GS1 – Government organizations
- GS2 – Nongovernment organizations
- GS3 – Network structure
- GS4 – Property-rights systems
- GS5 – Operational-choice rules
- * GS6 – Collective-choice rules
- GS7 – Constitutional-choice rules
- GS8 – Monitoring and sanctioning rules

Actors (A)

- A1 – Number of relevant actors
- A2 – Socioeconomic attributes
- A3 – History or past experiences
- A4 – Location
- * A5 – Leadership/entrepreneurship
- * A6 – Norms (trust-reciprocity)/social capital
- * A7 – Knowledge of SES/mental models
- * A8 – Importance of resource (dependence)
- A9 – Technologies available

Action situations: Interactions (I) → Outcomes (O)

- | | | |
|-----------------------------|---------------------------------|--|
| I1 – Harvesting | I6 – Lobbying activities | O1 – Social performance measures (e.g., efficiency, equity, accountability, sustainability) |
| I2 – Information sharing | I7 – Self-organizing activities | O2 – Ecological performance measures (e.g., overharvested, resilience, biodiversity, sustainability) |
| I3 – Deliberation processes | I8 – Networking activities | O3 – Externalities to other SESs |
| I4 – Conflicts | I9 – Monitoring activities | |
| Investment activities | I10 – Evaluative activities | |

Related ecosystems (ECO)

- 1 – Climate patterns
- ECO2 – Pollution patterns
- ECO3 – Flows into and out of focal SES

*** Required for sustainable systems**



Think of Atul Gowande and The Checklist Manifesto

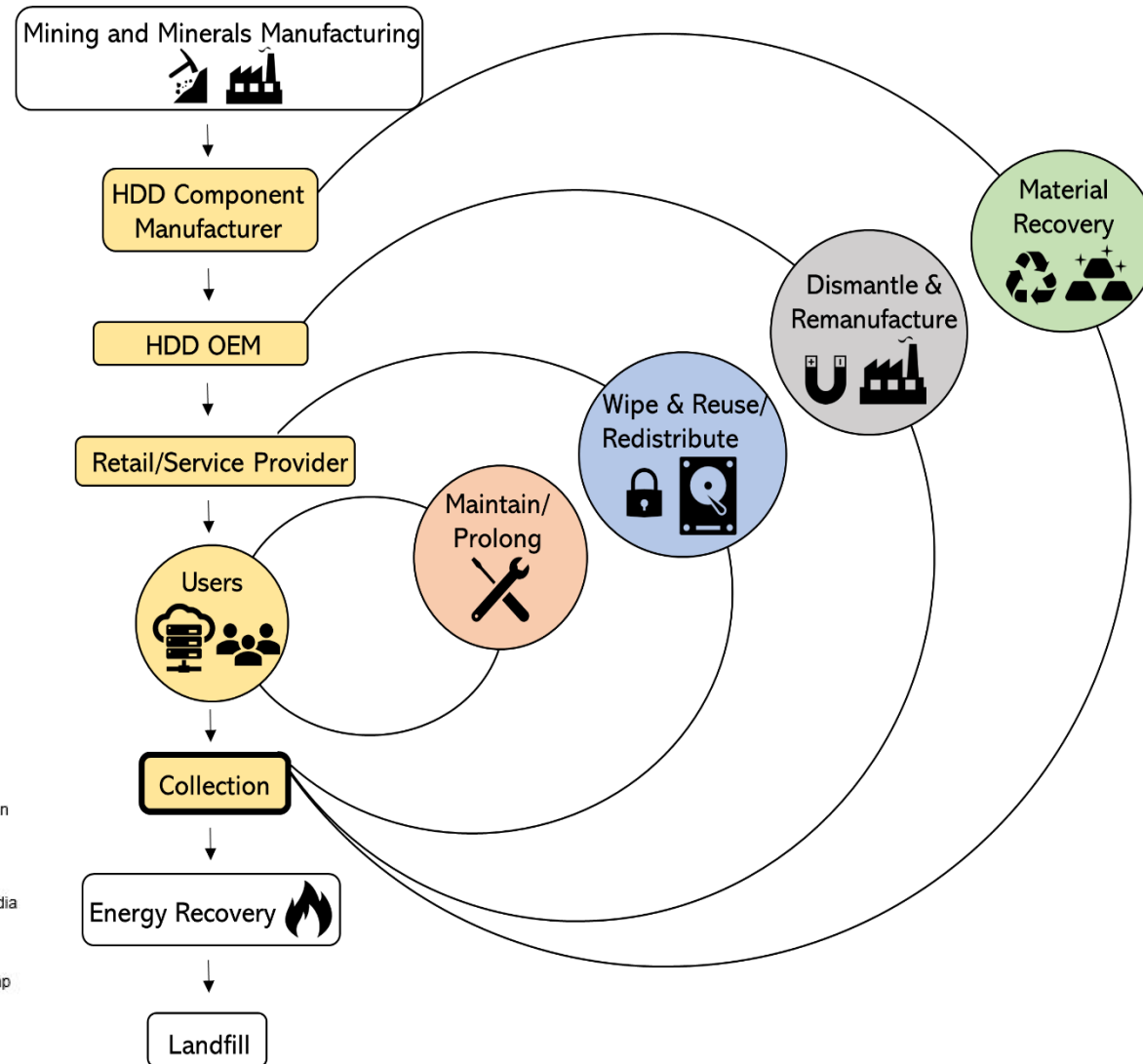
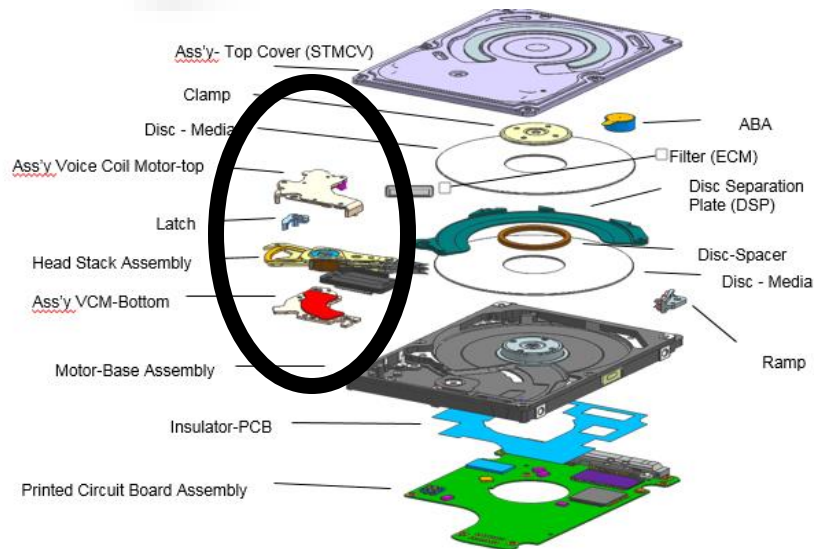
Creating a Circular Economy for Hard Disk Drives – A Shared Vision

Project Leaders:

Carol Handwerker (Purdue University)

Bill Olson (Seagate)

Creating a Circular Economy for Hard Disk Drives



Creating a Circular Economy for Hard Disk Drives

iNEMI Phase 2 project started in October 2017, completed September 2018

- **In-kind funding model**
- **System collaboration model:** self-assembling and self-managing group setting common goals (**Ostrom framework**)
- **Demonstration of circular economy for HDDs:** supply chain, economics, logistics, reducing life cycle costs

Members:

Ames Lab, Cascade Asset Management, **Cisco**, Critical Materials Institute, Echo Environmental, **Google**, Green Electronics Council, IBM/Geodis, Idaho National Lab, **Microsoft**, Momentum Technologies, Oak Ridge National Labs, Purdue University, **Seagate**, Teleplan, University of Arizona, Urban Mining Company



Members:

their goals, the positions they hold and the moves they can make

Members in the project had a common goal

HDD Manufacturers – Seagate

HDD Users – Cisco, Google, Microsoft

Authorized After-market Service Providers – Teleplan

Recyclers and IT Asset Management Companies – Geodis/IBM, Cascade Asset Management, Echo Environmental

Secondary Market Buyers and Sellers of HDDs – connected through recyclers and large HDD users

Magnet Manufacturers – connected through Seagate

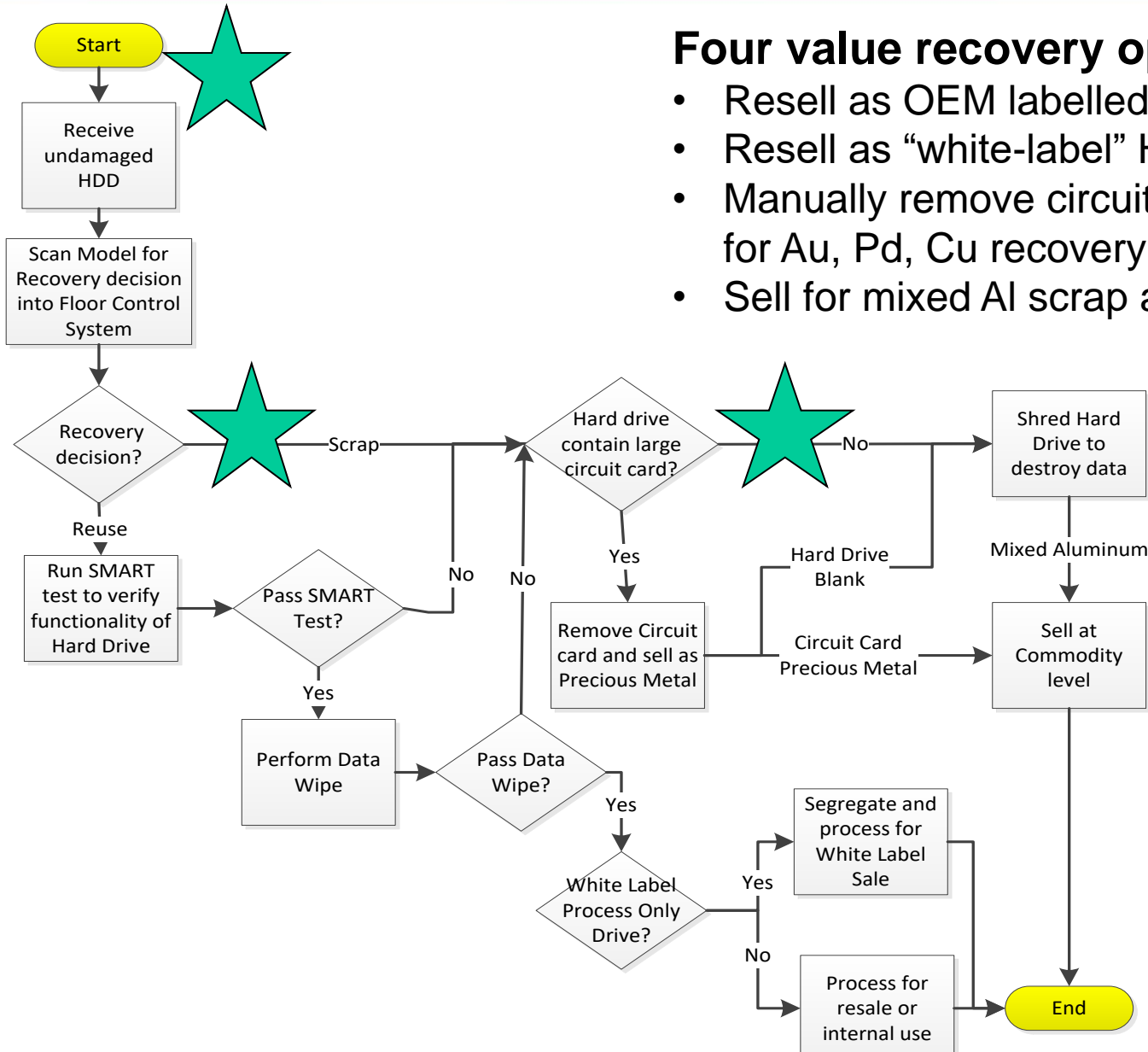
Smelters and Other Materials Recovery Organizations- Momentum Technologies, Urban Mining Corporation

After First-Market Users - consumers, data center, enterprise, cloud, computer – connected through HDD Users + AM Service Providers

Technology Developers – research organizations (national labs, universities, all the above) – CMI – Ames, INL, ORNL, Purdue

²⁰ **Standards organizations – GEC (EPEAT)**

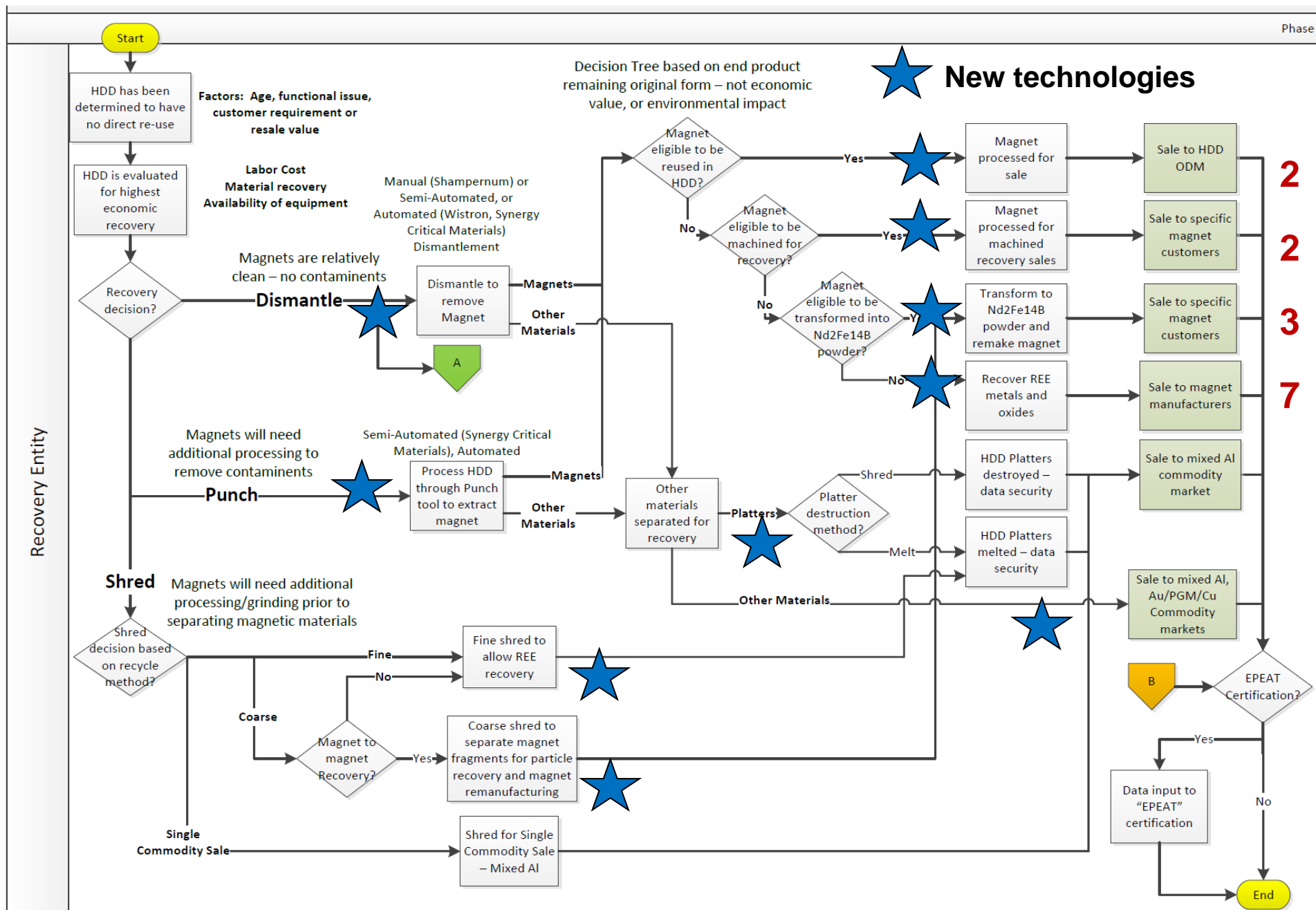
Decision Tree for Value Recovery from Used HDDs



Four value recovery options:

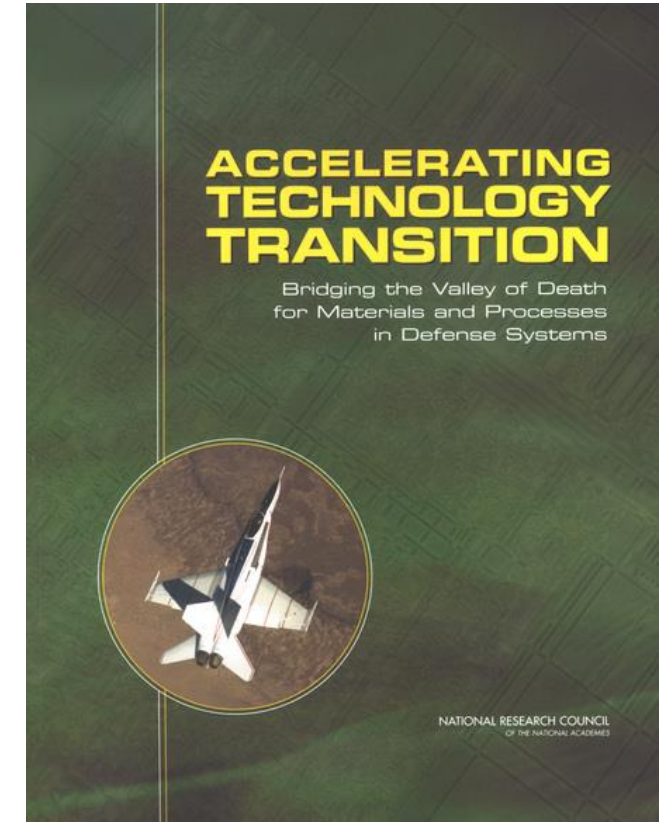
- Resell as OEM labelled HDD
- Resell as “white-label” HDD
- Manually remove circuit boards and sell for \$7-\$9/lb for Au, Pd, Cu recovery
- Sell for mixed Al scrap at \$0.25/lb as shred or whole

In iNEMI Project – 9 pathways



A New Model for Managing the Commons

- Students as a Commons
- Educators create the eco-system
- Not just what we teach, but
 - how we focus on shared resources
 - how we build and reinforce trust
 - how we implement an eco-system sustainability
 - ...
- **Next Steps: Propose a series of Workshops**
 - tools to use and models to test



- Creating a culture for innovation and rapid technology transition,
- Methodologies and approaches, and
- Enabling tools and databases.

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Extra Slides

Resulting Demonstration Projects

Demonstration Project	Leaders	Key Finding
HDD Coil Magnet Assembly Direct Reuse	Seagate/Google	HDD magnet assemblies can be effectively harvested and used to build new hard drives
HDD Direct Magnet Reuse	Oak Ridge National Laboratory	HDD magnets can be recovered undamaged in large numbers (>1MM/yr) and used in useful products (beyond HDD)
Magnets from Dismantled HDD	Urban Mining Company	Can harvest magnets from a range of HDDs in a commercially viable way
Oxides from EoL HDD Magnets	Momentum Technologies/Ames Lab	Demonstrated ability to produce REOs from different recovery paths with high purity
Moving from "Reuse or Shred" to "Reuse and Recover"	Microsoft/Google/Idaho National Lab	Identified economic and environmental values from wiping and resale/reuse

- **Project Page with final report, presentations, papers: https://www.inemi.org/value_recovery_2**
- **Environmental impacts of a circular recovery process for hard disk drive rare earth magnets**, K. Frost, I. Sousa, J. Larson, H. Jin, I. Hua, Resources, Conservation and recycling October 2021
- **Life cycle assessment of emerging technologies on value recovery from hard disk drives**, Jin, H., Frost, K., Sousa, I., Ghaderi, H., Bevan, A., Zakotnik, M., Handwerker, C.A., Resources, Conservation & Recycling, 157 (2020) Article Number: 104781

We posit

Two Additional Necessary Factors for Success

Actors have ***shared goals*** for the SYSTEM as well as individual goals for themselves that are explicitly articulated

Actors recognize that others' ***individual goals*** are important -
so that when there are disagreements or things get “hard”, we continue to work together to meet our shared goals

**This is explicitly what we developed in the
iNEMI Value Recovery project**